ABSTRACT

MANUFACTURING APPARATUS AND MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE~~SEMICONDUCTOR DEVICE MANUFACTURING DEVICE AND MANUFACTURING METHOD~~

A manufacturing apparatus (10) of a semiconductor device includes a stage (12), a mounting tool (20), a pressing mechanism (22), and a controller (16). The pressing mechanism (22) moves the mounting tool (20) in a vertical direction and applies a load to a chip (100). The controller (16) is configured to perform a first process and a detection process. In the first process, after bringing the chip (100) into contact and until a bump (104) melts, the chip (100) is heated by the mounting tool (20) and a command position P* of the pressing mechanism (22) is constantly updated so that a positional deviation ΔP* is constant. In the detection process, melting of the bump is detected based on a decrease in the pressing load.~~A semiconductor device manufacturing device (10) is provided with a stage (12), a mounting tool (20), a pressurizing mechanism (22) for causing the mounting tool (20) to be moved vertically to apply a load to a chip (100), and a controller (16). The controller (16) is configured to perform, after the chip (100) has landed and until a bump (104) melts: a first process in which the chip (100) is heated by the mounting tool (20) and a command position P* for the pressurizing mechanism (22) is updated, as required, so as to make a position deviation ΔP* constant; and a detection process for detecting melting of the bump on the basis of a decrease in a pressing load.~~

Figure 1